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| <i>Thong Nguyen (University of Illinois at Urbana Champaign), Xinying Wang (University of Illinois at Urbana Champaign), Xu Chen (University of Illinois at Urbana Champaign), and Jose Schutt-Aine (University of Illinois at Urbana Champaign)</i> | |
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| <i>Hui Liu (Intel Corporation), Qian Ding (Intel Corporation), and Penglin Liu (Intel Corporation)</i> | |
| Enhanced Reliability of a RF-SiP with Mold Encapsulation and EMI Shielding | 1902 |
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| | <i>Yi Zhou (Georgia Institute of Technology), Sridhar Sivapurapu (Georgia Institute of Technology), Rui Chen (Georgia Institute of Technology), Nahid Aslani Amoli (Georgia Institute of Technology), Mohamed Bellaredj (Georgia Institute of Technology), Madhavan Swaminathan (Georgia Institute of Technology), and Suresh K. Sitaraman (Georgia Institute of Technology)</i> |
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Multilayer Glass Substrate with High Density Via Structure for All Inorganic Multi-chip Module .1952.....
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Additive Laser Metal Deposition Onto Silicon for Enhanced Microelectronics Cooling .1970.....
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PCB Microstrip Line Far-End Crosstalk Mitigation by Surface Mount Capacitors .1989.....
Zhaoqing Chen (IBM Corporation)

New Cost-Effective Via-Last Approach by "One-Step TSV" After Wafer Stacking for 3D Memory Applications .1996.....
*Masaya Kawano (Institute of Microelectronics, A*STAR), Xiangy-Yu Wang (Institute of Microelectronics, A*STAR), and Qin Ren (Institute of Microelectronics, A*STAR)*

- Microstructure and Property Changes in Cu/Sn-58Bi/Cu Solder Joints During Thermomigration .2003.....
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- Simulation and Experimental Validations of EM/TM/SM Physical Reliability for Interconnects Utilized in Stretchable and Foldable Electronics .2009.....
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- A Complex Integrated Circuit Structure Transformation, Modeling and Simulation Method .2016.....
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- A Study on the Oxygen Plasma Treatment on the Peel Adhesion Strength and Solder Wettability of SnBi58 Based Anisotropic Conductive Films .2022.....
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- Electromigration-Induced -Sn Grain Rotation in Lead-Free Flip Chip Solder Bumps .2036.....
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- Low-Cost MT-Ferrule-Compatible Optical Connector for Co-packaged Optics Using Single-Mode Polymer Waveguide .2042.....
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- Characterization of Coated Silver Wire Bond Interface Using TEM .2048.....
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| Influence of Single/Double Sweeping Mode and Sweeping Voltage Increment/Polarity on Measurement of TSV Leakage Current .2061..... | |
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